

AMENDMENTS TO THE CLAIMS:

Kindly amend claims 1 and 7, as shown below.

This listing of claims will replace all prior versions and listings of claims in the Application:

Claim 1 (currently amended): A semiconductor device comprising:

a semiconductor chip mounted on a mounting substrate;

a first resin filling a gap between the semiconductor chip and the mounting substrate;

a stiffener surrounding the semiconductor chip, the stiffener being adhered to the mounting substrate with a first adhesive; and

a second resin filling a space between the semiconductor chip and the stiffener in contact with the first resin, the second resin being smaller in a thermal expansion coefficient than the first resin,

wherein the first resin and the second resin comprise an epoxy resin main component and an inorganic filler component and wherein the epoxy resin main component is the same in the first resin and the second resin and the inorganic filler component of the first resin is different in content amount than the inorganic filler component of the second resin.

Claim 2 (cancelled)

Claim 3 (cancelled)

Claim 4 (original): The semiconductor device as claimed in claim 1, wherein the first resin includes an underfill part filling the gap between the semiconductor chip and the mounting substrate, and a fillet part extended from a region of the semiconductor chip.

Claim 5 (previously presented): The semiconductor device as claimed in claim 1, wherein the first adhesive is larger in a thermal expansion coefficient than the second resin.

Claim 6 (original): The semiconductor device as claimed in claim 4, wherein the

second resin is in contact with inner walls of the stiffener, the fillet part, the mounting substrate and each of side faces of the semiconductor chip.

Claim 7 (currently amended): A semiconductor device comprising:

a semiconductor chip mounted on a mounting substrate;

a first resin filling a gap between the semiconductor chip and the mounting substrate;

a stiffener surrounding the semiconductor chip;

a second resin filling a space between the semiconductor chip and the stiffener in contact with the first resin, the second resin being smaller in a thermal expansion coefficient than the first resin; and

a lid for covering the stiffener and the semiconductor chip, wherein the lid is bonded to the stiffener and a backside of the semiconductor chip with a second adhesive,

wherein the first resin and the second resin comprise an epoxy resin main component and an inorganic filler component and wherein the epoxy resin main component is the same in the first resin and the second resin and the inorganic filler component of the first resin is different in content amount than the inorganic filler component of the second resin.

Claim 8 (original): The semiconductor device as claimed in claim 7, wherein the second resin is in contact with an inner wall of the lid.

Claim 9 (original): The semiconductor device as claimed in claim 1, wherein an elastic modulus of the second resin is larger than an elastic modulus of the first resin.

Claim 10 (withdrawn): The semiconductor device as claimed in claim 2, wherein the stiffener has a plurality of concave portions facing the mounting substrate.

Claim 11 (withdrawn): The semiconductor device as claimed in claim 10, wherein a planer shape of the stiffener is rectangular, and the concave portion is formed on each corner of the stiffener.

Claim 12 (withdrawn): The semiconductor device as claimed in claim 10, wherein each of concave portions is filled with a resin the same as the second resin.

Claim 13 (withdrawn): The semiconductor device as claimed in claim 2, wherein the stiffener end surface facing the mounting substrate is convexo-concave, and a gap between the mounting substrate and concave portion of the stiffener end surface is filled with a first adhesive.

Claim 14 (withdrawn): The semiconductor device as claimed in claim 2, wherein the stiffener end surface facing the mounting substrate is convexo-concave, and a gap between the mounting substrate and concave portion of the stiffener end surface is filled with a resin the same as the second resin.

Claim 15 (withdrawn): The semiconductor device as claimed in claim 2, wherein the stiffener end surface facing the mounting substrate is convexo-concave, the mounting substrate includes a first metal layer in a region facing the stiffener, the stiffener includes a second metal layer on a surface of a convex portion, and the mounting substrate and the convex portion of the stiffener are connected to each other by a low-melting alloy.

Claim 16 (previously presented): The semiconductor device as claimed in claim 1, wherein the stiffener is made of a material selected from the group consisting of Cu, SUS, Al, alumina, silicon, and aluminum nitride.

Claim 17 (original): The semiconductor device as claimed in claim 1, wherein each of the first resin and the second resin essentially contains a resin selected from a group consisting of epoxy, polyolefin, silicon, cyanate ester, polyimide, polynorbornene resins.

Claim 18 (withdrawn): The semiconductor device as claimed in claim 1, wherein a gap member different from the first adhesive is partially arranged between the mounting substrate and the stiffener.

Claim 19 (withdrawn): The semiconductor device as claimed in claim 18, wherein the gap member is made of a low-melting alloy.

Claim 20 (previously presented): The semiconductor device as claimed in claim 1, wherein the semiconductor chip is mounted on the mounting substrate through flip chip bonding.

HAYES SOLOWAY P.C.
3450 E. SUNRISE DRIVE,
SUITE 140
TUCSON, AZ 85718
TEL. 520.882.7623
FAX. 520.882.7643

175 CANAL STREET
MANCHESTER, NH 03101
TEL. 603.668.1400
FAX. 603.668.8567